# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

| HP Compaq Pro 6300 All-in-One Business PC |

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm PCA</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries RTC BATTERIES</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps LCD</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>N/A</td>
<td>0</td>
</tr>
</tbody>
</table>

PSG instructions for this template are available at [EL-MF877-01](#).
Components, parts and materials containing refractory ceramic fibers | N/A | 0  
Components, parts and materials containing radioactive substances | N/A | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Hexagonal Screwdriver (T15)</td>
<td>T15 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Philips Screwdriver</td>
<td>2# 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Slotted Screwdriver</td>
<td>2# 2.55-3.00kgf.cm</td>
</tr>
<tr>
<td>Knife</td>
<td></td>
</tr>
<tr>
<td>Allen Wrench</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Disassembly process – SUPPORT/HOUSING  
2. Disassembly process – PANEL  
3. Disassembly process – MAINBOARD  
4.  
5.  
6.  
7.  
8.  

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1.
Disassembly process: Support/Housing

1. Separate the support cover.
2. Separate the 4 rubber pads.
3. Separate the base cover by loosening 4 screws.
4. Separate the metal hinge by loosening 8 screws.
5. Separate the metal support by loosening 2 screws.
6. Separate the rotor plate by loosening 4 screws.
7. Separate the metal base weight by loosening 4 screws.
8. Separate the metal weight form plastic base.
9. Remove the washer of rotor.

(To be continued)

PSG instructions for this template are available at EL-MF877-01
Disassembly process

- Support/Housing

Cont.

Remove the cover of plug room.

Loosen 1 screw to remove the rear upper cover.

Push the button to push the rear upper cover.

Separate the front frame by loosening 15 screws.

Separate the two-side cover.

Loosen 1 screw to remove the rear bottom cover.

Separate the metal frame from side cover.

Tear off the sticker of connector frame.

Separate the metal frame from rear cover.

(To be continued)
Disassembly process - Support/Housing Cont.

Tear off the cover tape of speaker.

Tear off the foam tape from front frame.

Remove the PCBA and plastic cover.

Completed disassembly.

Separate the metal decoration form front frame.

Separate the gray frame form front frame.
2. Disassembly process - Panel

Separate the panel from the frame by loosening 4 screws.

Tear the tape from PCBA.

Separate metal frame.

Remove all optical plastic film.

Separate the plastic frame of panel.

Separate the PCBA by loosening 3 screws.

Separate the PCBA of LED.

Completed disassembly.

PSG instructions for this template are available at EL-MF877-01
Disassembly process - Mainboard

Remove the metal cover.

Loosen 4 screws to remove the speaker and washer.

Separate the connector by loosening 1 screw.

Separate the DVD module by loosening 3 screws.

Separate PCBA on DVD by loosening 2 screws and remove the plastic cover.

Loosen 3 screws to remove the fan.

Separate the metal sink by loosening 5 screws.

Loosen 1 screw to remove the power plug.

Separate the PCBA by loosening 10 screws.

(To be continued)
Remove all cables and heatproof mat.

Loosen 2 screws to remove the plug for PCBA.

Separate the power supplier by loosening 1 screw.

Remove the foam tape.

Remove the frame and HD.

Push out the power supplier.

Remove the heat sink.

Separate the fixer of CPU by loosening 3 screws.

Remove the RAM and HD.

(To be continued)
Disassembly process - Mainboard Cont.

Remove the card edge by loosening 2 screws. → Remove the battery. → Remove the metal frame from PCBA.

Completed disassembly.

Summary of disassembly assessment
<table>
<thead>
<tr>
<th>Item</th>
<th>Findings</th>
</tr>
</thead>
<tbody>
<tr>
<td>Disassembly time</td>
<td>45 minutes by manual disassembly</td>
</tr>
<tr>
<td>Tools used for manual disassembly</td>
<td>- Hexagonal Screwdriver</td>
</tr>
<tr>
<td></td>
<td>- Philips Screwdriver</td>
</tr>
<tr>
<td></td>
<td>- Slotted Screwdriver</td>
</tr>
<tr>
<td></td>
<td>- Knife</td>
</tr>
<tr>
<td></td>
<td>- Allen Wrench</td>
</tr>
<tr>
<td>Connection techniques found on submitted sample</td>
<td>- Screw x 87</td>
</tr>
<tr>
<td></td>
<td>- Combination x 17</td>
</tr>
<tr>
<td></td>
<td>- Adherence x 20</td>
</tr>
</tbody>
</table>